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PU/PHY/NS/DST-NANO/12-13/127

Date: 14-03-2013

Sir,
Sub: Quotation for **SPUTTERING TARGETS** - Reg.

Sealed quotations are invited so as to reach the undersigned on or before **28.03.2011** at **12.00 Noon and will be opened on the same day at 03.00 P.M.**, as per the list enclosed below mentioned subject to the following terms and conditions.

1. The quotations should be valid for three months.
2. No advance freight insurance coverage will be done.
3. Prices should be inclusive of all charges towards packing, freight, transits, excise duty, insurance, octroi, but exclusive of sales tax only and the supply should be made at our premises.
4. Payment will be made within 30 days of the receipt of the articles in good condition.
5. Demonstration should be done at our laboratory.
6. The university has the right to accept the rates of any one or all the articles required as may be considered necessary.

Name of the equipment: **Sputtering Targets**

Detailed specifications:

Item	Product	Material	Shape	Quantity
1	Sputtering Target	Li ₄ Ti ₅ O ₁₂ 99.99%	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
2	Sputtering Target	Lithium Phosphorus Oxynitride (LIPON) 99.99 %	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
3	Sputtering Target	LiCoO ₂ 99.99 %	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
4	Sputtering Target	LiMn ₂ O ₄ 99.99%	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
5	Sputtering Target	Li _{1.3} Al _{0.3} Ti _{1.7} (PO ₄) ₃ 99.99%	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
6	Sputtering Target	Li [Ni _{1/3} Co _{1/3} Mn _{1/3}]O ₂ 99.99 %	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
7	Sputtering Target	LiMnPO ₄ 99.99%	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
8	Sputtering Target	Cu 99.99%	2" diameter with 2mm, 3mm & 4mm thick bonded to a OFHC Copper backing plate	1
9	Sputtering Target	Ti 99.99%	2" diameter x 4mm Thick	1
10	Sputtering Target	Silicon Wafers	Orientation: <100>+/-0.5degree Type/Dopant: N Type, P doped Size: with 2" dia. x 0.5 mm thick and 4" dia. x 0.5 mm thick Surface: One side polished, Resistivity: with 0.001~ 0.005ohm-cm, ~1ohm-cm and 1~ 5 ohm-cm	2 (25pcs packets)
11	Sputtering Target	Au 99.99 %	2" diameter x 4mm thick	1
12	Sputtering Target	Pt 99.99 %	2" diameter x 4mm thick	1

Thanking you,

Yours faithfully

Prof. N.Satyanarayana
(Principal Investigator- DST-NANO MISSION)